

									1	
LOC	DIST	REVISIONS								
H	—	P	LTR	DESCRIPTION				DATE	DWN	APVD
			L	REVISED PER ECO-13-014710				07NOV2013	SY	FY

NOTES:

- 1

MATERIAL CONTACTS; PHOSPHORBRONZE

MATERIAL HOUSING; GLASSFILLED POLYESTER (GRAY)
- 2

GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27µm NICKEL MIN. AND ACTION PIN: 0,5µm TIN-LEAD MIN.

FOR PLATING OF MATING SURFACES SEE APPLICABLE SPECIFICATION REFERENCE FOR EACH DASH NUMBER.
- 3

CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101

PERFORMANCE LEVEL 2.
- 4

CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101

PERFORMANCE LEVEL 1.
- 5

CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA

GR-1217-CORE QUALITY LEVEL III, CENTRAL OFFICE APPLICATIONS.
- 6

CONNECTOR LUBRICATED WITH TELCORDIA APPROVED LUBRICANT.
- 8

ASSEMBLY PRINTED WITH P/N AND DATECODE

THE MARKING CAN APPEAR ON THE FRONT SIDE OR BACK SIDE.
- 9

HOLE PATTERN FOR FEMALE CONNECTOR TYPE B-22 COLUMNS

110 PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID
- 10

ROW "f" 11 PLATED THROUGH HOLES FOR UPPERSHIELD
- 11

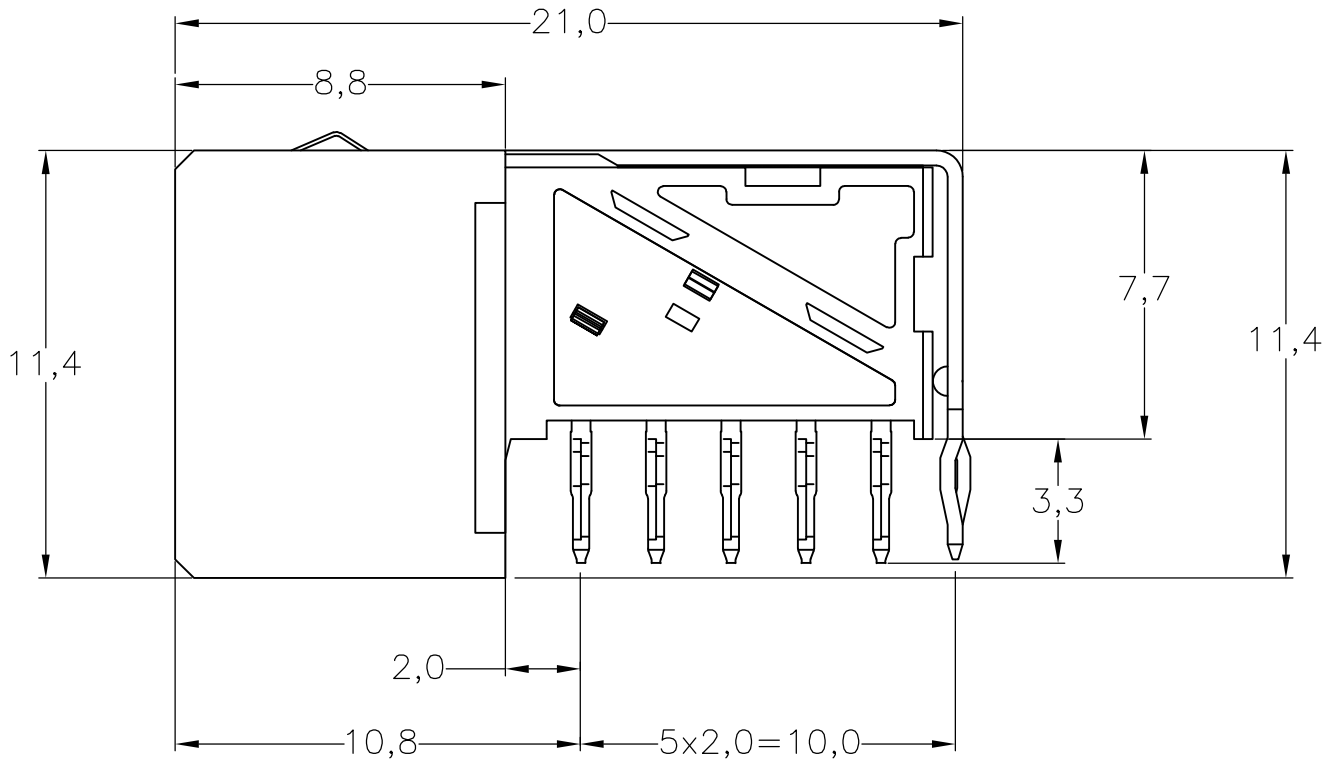
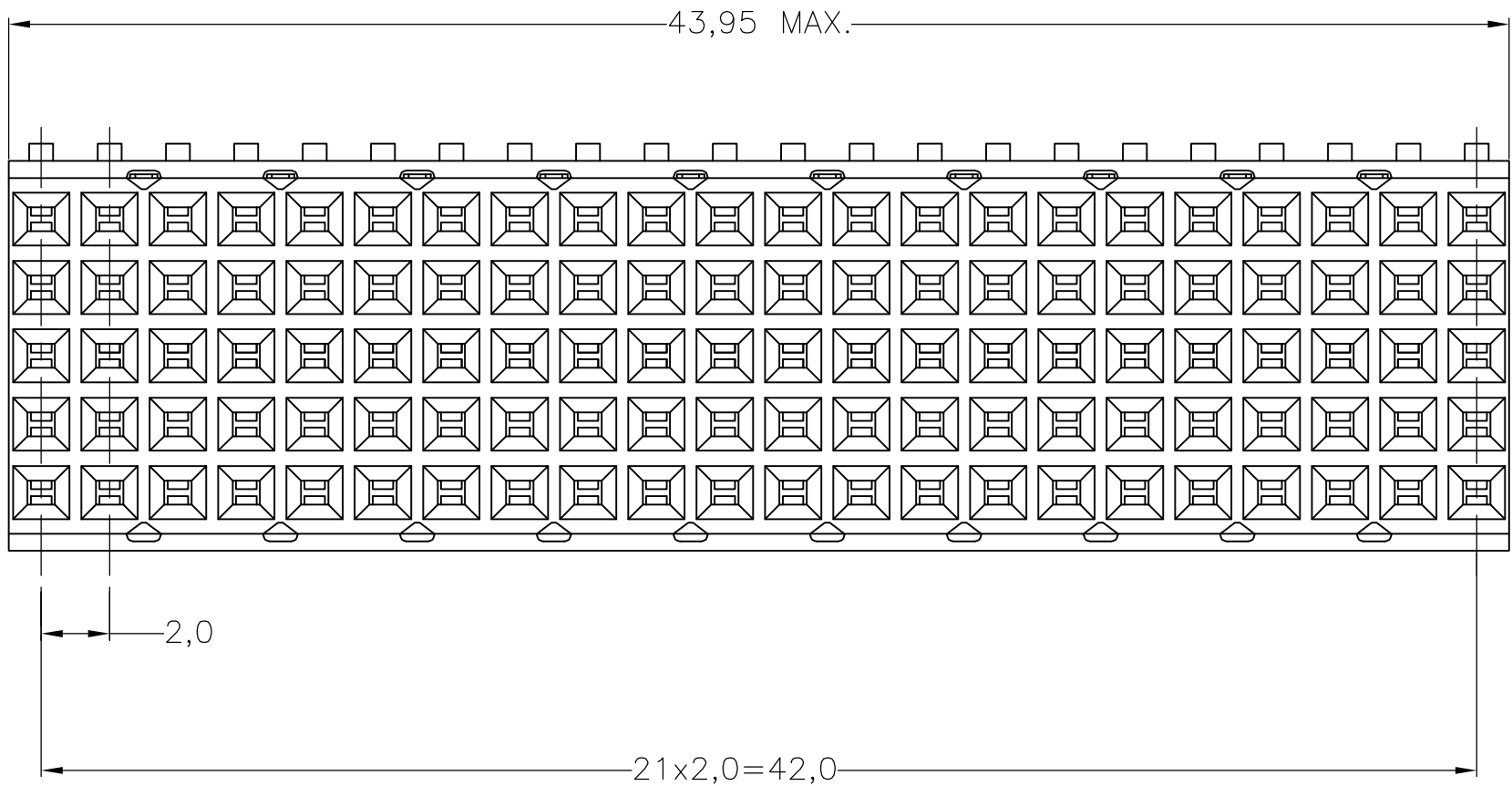
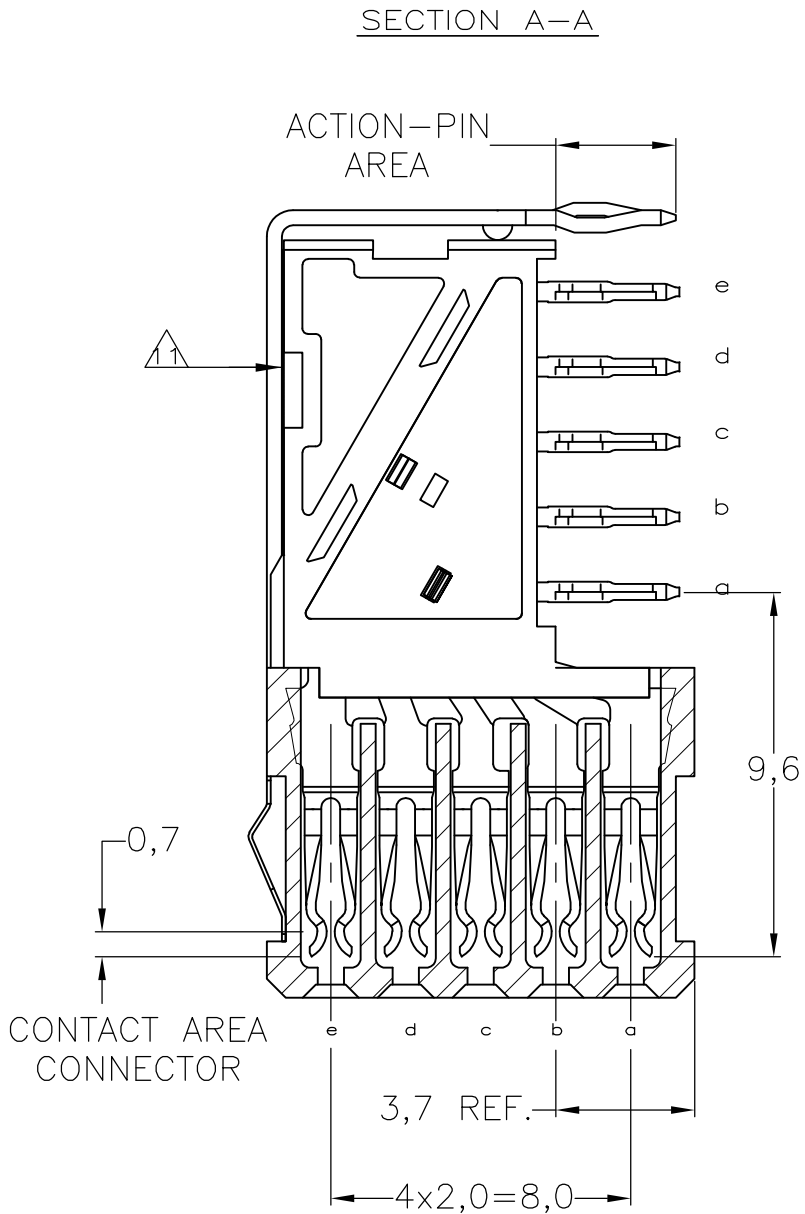
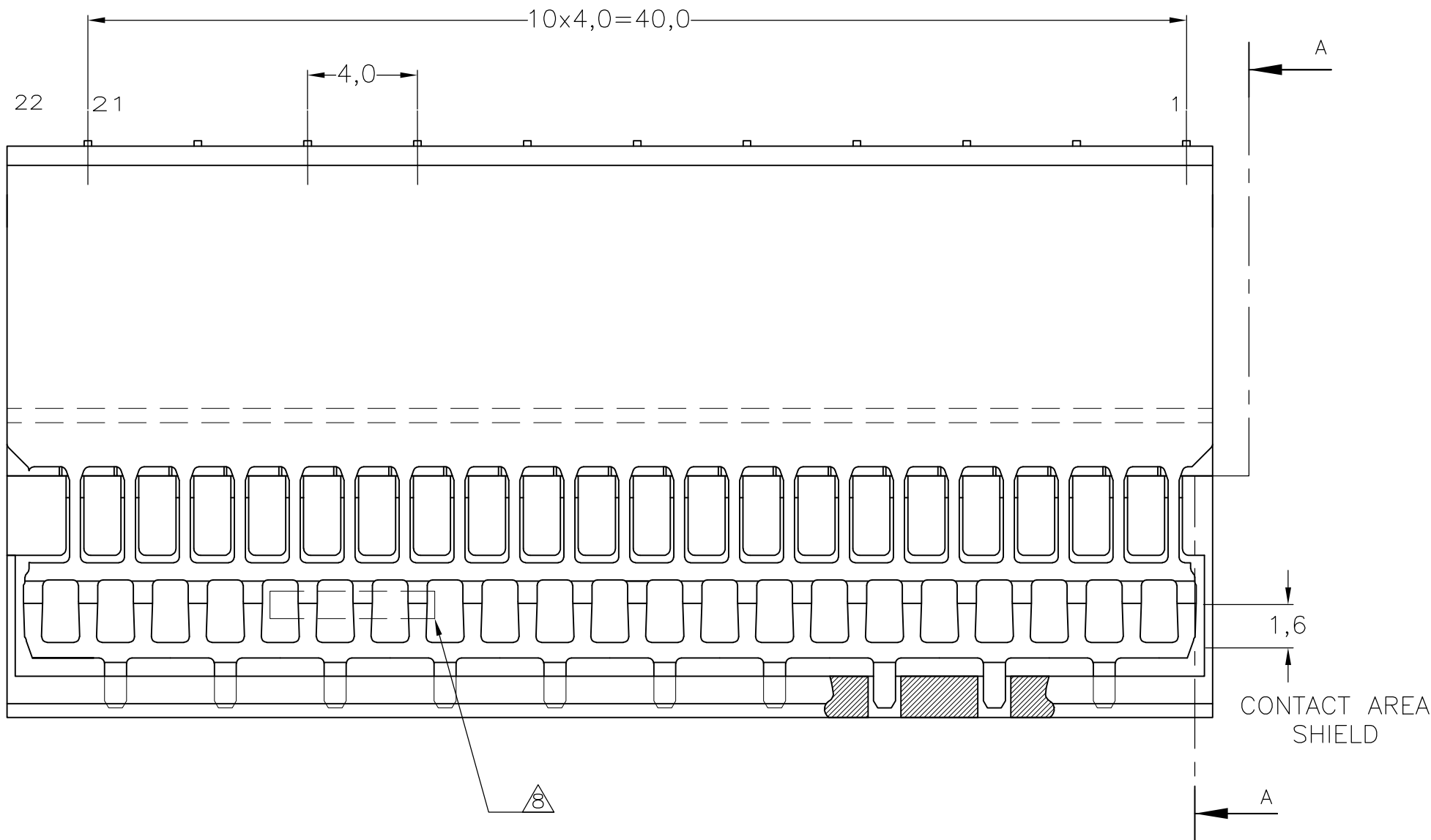
SHIELD MOUNTED ON CONNECTOR WITH DOUBLE SIDED

ADHESIVE TAPE OR ADHESIVE
- 12

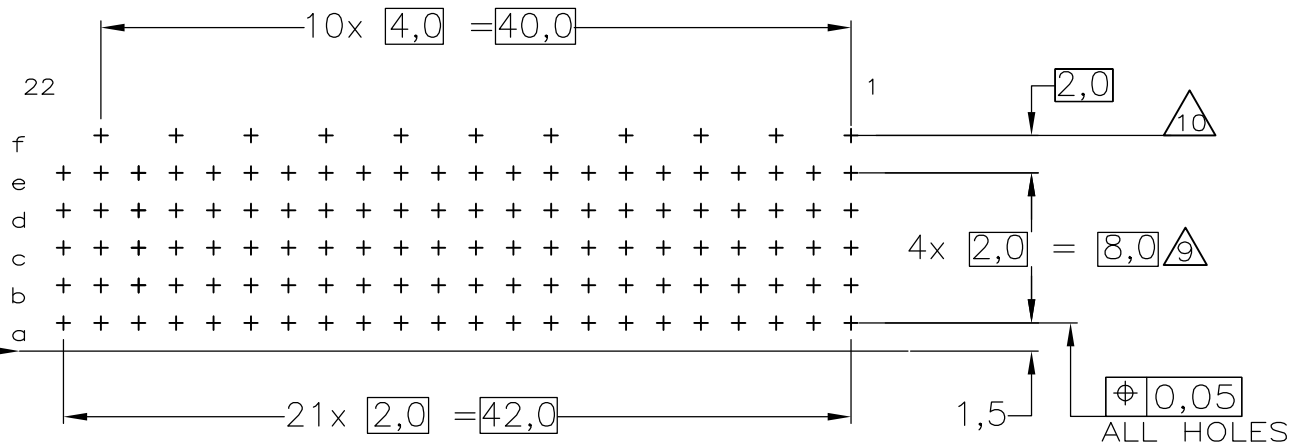
BASIC P.N. LOWERSHIELD: 352468
- 13

OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- 14

0.76um MIN GOLD PLATING ON MATING SURFACES

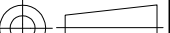


SCALE 2,5:1
COMPONENT SIDE AS SHOWN
RECOMMENDED PCB-HOLE LAY-OUT



P.C.B. HOLE DIM. ACTION PIN
FOR DETAILS SEE
APPLICATION SPECIFICATION

EDGE OF P.C.BOARD

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN D. TRUREN	23SEP96	 TE Connectivity	
DIMENSIONS:		CHK —	—		
mm	TOLERANCES, UNLESS OTHERWISE SPECIFIED:	APVD —	—	NAME Z-PACK 2MM HM TYPE B - 22 COLUMNS PRE-SHIELDED RECEPTACLE	
	Ø PLG ±				

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[3-352152-0](#)